



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-06-30
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32L496VET3	261L*461XXXB	A	9991	2025-06-30
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	672	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
QFP	14x14	100	Gull wing	
Comment	Package : 1L LQFP 100 14x14x1.4 1 0086901			

QueryList : RoHS Directive 2011/65/EU - 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
,		

QueryList : REACH-21st January 2025				Response
QUERY				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	261L*461XXXB		672.4282		6000000.0	1000000.0
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	16.852	mg	supplier	die	Silicon (Si)	7440-21-3		16.444	mg	975755	25355.04
				supplier	metallization	Aluminium (Al)	7429-90-5		0.019	mg	1151	29.91
				supplier	metallization	Copper (Cu)	7440-50-8		0.173	mg	10288	267.33
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.056	mg	3309	85.98
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	144	3.74
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	72	1.87
				supplier	Passivation	Silicon Nitride	12033-89-5		0.044	mg	2590	67.30
				supplier	Passivation	Silicon Oxide	7631-86-9		0.113	mg	6691	173.87
				supplier	Leadframe	Copper (Cu)	7440-50-8		174.610	mg	919000	258006.62
Leadframe (C7025 + Ag)	Copper & its alloys	190.000	mg	supplier	Leadframe	Nickel (Ni)	7440-02-0		5.890	mg	31000	8703.16
				supplier	Leadframe	Silicon (Si)	7440-21-3		2.280	mg	12000	3368.97
				supplier	Leadframe	Magnesium (Mg)	7439-95-4		0.570	mg	3000	842.24
				supplier	Leadframe	Silver (Ag)	7440-22-4		6.650	mg	35000	9826.15
				supplier	Leadframe	Silver (Ag)	7440-22-4		2.706	mg	779000	4182.73
Glue Epoxy (EN-4900G)	Precious metals	3.474	mg	supplier	Glue or tape	Silver (Ag)	7440-22-4		2.706	mg	779000	4182.73
				supplier	Glue or tape	Cresol Novolac Epoxy Resins	Proprietary		0.087	mg	25000	134.23
				supplier	Glue or tape	Bisphenol A Diacrylate	Proprietary		0.212	mg	61000	327.53
				supplier	Glue or tape	Dicyclopentenyl group containing Acrylate	Proprietary		0.191	mg	55000	295.31
				supplier	Glue or tape	Butadiene copolymer	Proprietary		0.035	mg	10000	53.69
				supplier	Glue or tape	Polybutadiene epoxidized derivative	Proprietary		0.191	mg	55000	295.31
				supplier	Glue or tape	Peroxy Ketals	Proprietary		0.017	mg	5000	26.85
				supplier	Glue or tape	Substitutedalkoxyalkyl trimethoxysilane	Proprietary		0.017	mg	5000	26.85
				supplier	Glue or tape	Methacrylate multialkoxy-substitutedalkyl ester	Proprietary		0.017	mg	5000	26.85
Bonding wire (Cu)	Precious metals	1.202	mg	supplier	Bonding wire	Copper (Cu)	7440-50-8		1.160	mg	965500	1836.08
				supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.037	mg	31000	58.95
				supplier	Bonding wire	Silver (Ag)	7440-22-4		0.004	mg	3500	6.66
				supplier	Bonding wire	Silver (Ag)	7440-22-4		0.004	mg	3500	6.66
Encapsulation (EME-G631SH)	M-011 Other inorganic materials	440.000	mg	supplier	Molding Compound	2,2'-((3,3',5,5'-Tetramethyl-1,1'-biphenyl)-4,4'-diyl	85954-11-6		17.600	mg	40000	26204.58
				supplier	Molding Compound	Epoxy resin	Proprietary		8.800	mg	20000	13102.29
				supplier	Molding Compound	Phenol Resin	Proprietary		33.000	mg	75000	49133.59
				supplier	Molding Compound	Silica(Amorphous) A	60676-86-0		312.180	mg	709500	464803.79
				supplier	Molding Compound	Silica(Amorphous) B	7631-86-9		66.000	mg	150000	98267.19
				supplier	Molding Compound	Carbon black	1333-86-4		2.420	mg	5500	3603.13
External Plating (Sn)	M-011 Other inorganic materials	20.900	mg	supplier	Matte Sn	Tin (Sn)	7440-31-5		20.898	mg	999900	30879.10
				supplier	Matte Sn	Impurities	Proprietary		0.002	mg	100	3.09